IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for establishing an electrical contact with at least one semiconductor device, comprising:

establishing an electrical contact between a first member of an electrical connector and a contact that is in electrical communication with the at least one semiconductor device; and

magnetically drawing at least one of ~~said~~the first member and ~~said~~the contact toward the other of ~~said~~the first member and ~~said~~the contact.

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2. (Currently amended) The method of claim 1, wherein ~~said~~ magnetically drawing is effected in a direction substantially normal to a plane of ~~said~~the contact.

3. (Currently amended) The method of claim 1, wherein ~~said~~ magnetically drawing is effected in a direction substantially normal to a plane of a substrate upon which ~~said~~the contact is carried.

4. (Currently amended) The method of claim 1, wherein ~~said~~ magnetically drawing is effected by positioning a second member of ~~said~~the electrical connector opposite ~~said~~the first member.

5. (Currently amended) The method of claim 4, wherein ~~said~~ magnetically drawing is effected by magnetically attracting at least one of ~~said~~the first member and ~~said~~the second member toward at least the other of ~~said~~the first member and ~~said~~the second member.

6. (Currently amended) The method of claim 4, wherein ~~said~~ magnetically drawing comprises securing ~~said~~the first and second members to a substrate upon which ~~said~~the contact is carried.

7. (Currently amended) The method of claim 1, wherein ~~said~~ magnetically drawing comprises magnetically securing ~~said~~the first member to ~~said~~the contact.

8. (Currently amended) A method for stress testing a plurality of semiconductor devices carried upon a common substrate and in communication with common ground and power contacts, comprising:

establishing electrical contact between a first member of an electrical connector and at least one contact of the ground contact and the power contact; and

magnetically drawing at least one of ~~said~~the first member and ~~said~~the at least one contact toward the other of ~~said~~the first member and ~~said~~the at least one contact.

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9. (Currently amended) The method of claim 8, wherein ~~said~~ magnetically drawing is effected in a direction substantially normal to a plane of the common substrate.

10. (Withdrawn)

11. (Currently amended) The method of claim 8, wherein ~~said~~ magnetically drawing comprises positioning a second member of ~~said~~the electrical connector opposite the substrate from ~~said~~the first member.

12. (Currently amended) The method of claim 11, wherein at least one of ~~said~~the first member and ~~said~~the second member is drawn toward at least the other of ~~said~~the first member and ~~said~~the second member.

13. (Currently amended) The method of claim 12, wherein ~~said~~ magnetically drawing comprises magnetically attracting at least one of ~~said~~the first member and ~~said~~the second member toward at least the other of ~~said~~the first member and ~~said~~the second member.

14. (Currently amended) The method of claim 8, wherein ~~said~~ magnetically drawing comprises magnetically securing ~~said~~the first member to ~~said~~the at least one contact.

15. (Currently amended) The method of claim 8, wherein ~~said~~ magnetically drawing comprises securing at least ~~said~~the first member in position relative to the substrate.

16. (Currently amended) The method of claim 8, further comprising:
electrically connecting another first member of another electrical connector to another of the ground contact and the power contact; and
magnetically drawing ~~said~~the another first member toward ~~said~~the another contact.

17. (Currently amended) The method of claim 16, further comprising:
applying a substantially constant amount of current to each semiconductor device of the plurality of semiconductor devices through ~~said~~the first member and ~~said~~the another first member.

18. (Original) The method of claim 17, further comprising:
heating each of the plurality of semiconductor devices.

19. (Currently amended) The method of claim 18, wherein ~~said~~ heating comprises cycling a temperature of each of the plurality of semiconductor devices.

20. (Currently amended) The method of claim 18, wherein ~~said~~ heating comprises varying a temperature of each of the plurality of semiconductor devices.